

1.2A DUAL HIGH-SPEED MOSFET DRIVERS

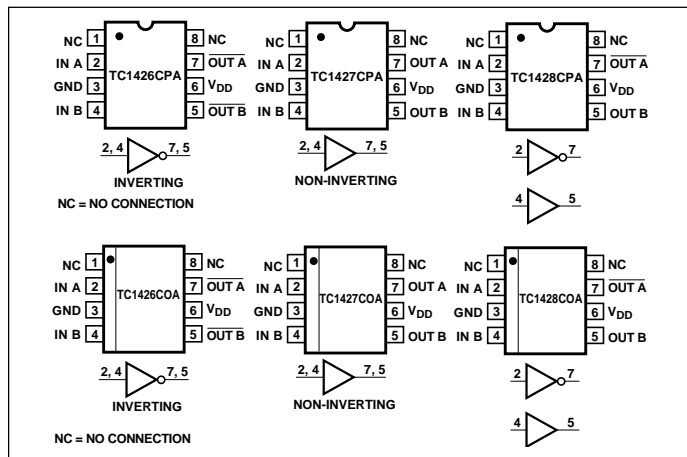
FEATURES

- Low Cost
- Latch-Up Protected: Will Withstand 500 mA Reverse Output Current
- ESD Protected ±2 kV
- High Peak Output Current 1.2A Peak
- High Capacitive Load Drive Capability 1000pF in 38nsec
- Wide Operating Range 4.5V to 16V
- Low Delay Time 75nsec Max
- Logic Input Threshold Independent of Supply Voltage
- Output Voltage Swing to Within 25mV of Ground or V_{DD}
- Low Output Impedance 8Ω

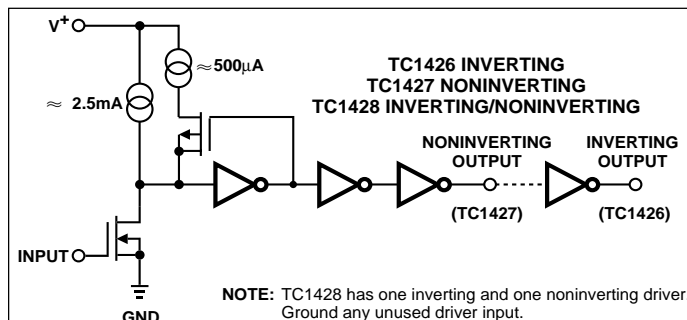
APPLICATIONS

- Power MOSFET Drivers
- Switched Mode Power Supplies
- Pulse Transformer Drive
- Small Motor Controls
- Print Head Drive

PIN CONFIGURATIONS



FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

The TC1426/27/28 are a family of 1.2A dual high-speed drivers. CMOS fabrication is used for low power consumption and high efficiency.

These devices are fabricated using an epitaxial layer to effectively short out the intrinsic parasitic transistor responsible for CMOS latch-up. They incorporate a number of other design and process refinements to increase their long-term reliability.

The TC1426 is compatible with the bipolar DS0026, but only draws 1/5 of the quiescent current. The TC1426/27/28 are also compatible with the TC426/27/28, but with 1.2A peak output current rather than the 1.5A of the TC426/27/28 devices.

Other compatible drivers are the TC4426/27/28 and the TC4426A/27A/28A. The TC4426/27/28 have the added feature that the inputs can withstand negative voltage up to 5V with diode protection circuits. The TC4426A/27A/28A have matched input to output leading edge and falling edge delays, tD1 and tD2, for processing short duration pulses in the 25 nanoseconds range. All of the above drivers are pin compatible.

The high-input impedance TC1426/27/28 drivers are CMOS/TTL input-compatible, do not require the speed-up needed by the bipolar devices, and can be directly driven by most PWM ICs.

This family of devices is available in inverting and non-inverting versions. Specifications have been optimized to achieve low-cost and high-performance devices, well-suited for the high-volume manufacturer.

ORDERING INFORMATION

Part No.	Package	Temp. Range
TC1426COA	8-Pin SOIC	0°C to +70°C
TC1426CPA	8-Pin Plastic DIP	0°C to +70°C
TC1427COA	8-Pin SOIC	0°C to +70°C
TC1427CPA	8-Pin Plastic DIP	0°C to +70°C
TC1428COA	8-Pin SOIC	0°C to +70°C
TC1428CPA	8-Pin Plastic DIP	0°C to +70°C

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ABSOLUTE MAXIMUM RATINGS* (Notes 1, 2 and 3)

Power Dissipation ($T_A \leq 70^\circ\text{C}$)	
Plastic DIP	730W
SOIC	470mW
Derating Factor	
Plastic DIP	8mW/ $^\circ\text{C}$
SOIC	4mW/ $^\circ\text{C}$
Supply Voltage	18V
Input Voltage, Any Terminal ($V_{DD} + 0.3\text{V}$) to ($\text{GND} - 0.3\text{V}$)	
Operating Temperature:	
C Version	0°C to $+70^\circ\text{C}$
E Version	-40°C to $+85^\circ\text{C}$

Maximum Chip Temperature	$+150^\circ\text{C}$
Storage Temperature	$+65^\circ\text{C}$ to $+150^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)	$+300^\circ\text{C}$

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS: $T_A = 25^\circ\text{C}$ with $4.5\text{V} \leq V_{DD} \leq 16\text{V}$ unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Input						
V_{IH}	Logic 1, Input Voltage		3	—	—	V
V_{IL}	Logic 0, Input Voltage		—	—	0.8	V
I_{IN}	Input Current	$0\text{V} \leq V_{IN} \leq V_{DD}$	-1	—	1	μA
Output						
V_{OH}	High Output Voltage	Test Figures 1 and 2	$V_{DD} - 0.025$	—	—	V
V_{OL}	Low Output Voltage	Test Figures 1 and 2	—	—	0.025	V
R_O	Output Resistance	$V_{IN} = 0.8\text{V}$, $V_{IN} = 3\text{V}$, $I_{OUT} = 10\text{ mA}$, $V_{DD} = 16\text{V}$	—	12	18	W
I_{PK}	Peak Output Current		—	1.2	—	A
I	Latch-Up Current	Withstand Reverse Current	> 500	—	—	mA
Switching Time (Note 1)						
t_R	Rise Time	Test Figures 1 and 2	—	—	35	nsec
t_F	Fall Time	Test Figures 1 and 2	—	—	25	nsec
t_{D1}	Delay Time	Test Figures 1 and 2	—	—	75	nsec
t_{D2}	Delay Time	Test Figures 1 and 2	—	—	75	nsec
Power Supply						
I_S	Power Supply Current	$V_{IN} = 3\text{V}$ (Both Inputs)	—	—	9	mA
		$V_{IN} = 0\text{V}$ (Both Inputs)	—	—	0.5	

Note: 1. Switching times guaranteed by design.

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ELECTRICAL CHARACTERISTICS: Over operating temperature range with $4.5V \leq V_{DD+} \leq 16V$ unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Input						
V_{IH}	Logic 1, Input Voltage		3	—	—	V
V_{IL}	Logic 0, Input Voltage		—	—	0.8	V
I_{IN}	Input Current	$0V \leq V_{IN} \leq V_{DD}$	- 10	—	10	μA
Output						
V_{OH}	High Output Voltage	Test Figures 1 and 2	$V_{DD} - 0.025$	—	—	V
V_{OL}	Low Output Voltage	Test Figures 1 and 2	—	—	0.025	V
R_O	Output Resistance	$V_{IN} = 0.8V,$ $I_{OUT} = 10mA, V_{DD} = 16V$	—	15	23	W
		$I_{OUT} = 10mA, V_{DD} = 16V$			10	18
I	Latch-Up Current	Withstand Reverse Current	> 500	—	—	mA
Switching Time (Note 1)						
t_R	Rise Time	Test Figures 1 and 2	—	—	60	nsec
t_F	Fall Time	Test Figures 1 and 2	—	—	40	nsec
t_{D1}	Delay Time	Test Figures 1 and 2	—	—	125	nsec
t_{D2}	Delay Time	Test Figures 1 and 2	—	—	125	nsec
Power Supply						
I_S	Power Supply Current	$V_{IN} = 3V$ (Both Inputs)	—	—	13	mA
		$V_{IN} = 0V$ (Both Inputs)	—	—	0.7	

Note: 1. Switching times guaranteed by design.

SUPPLY BYPASSING

Large currents are required to charge and discharge capacitive loads quickly. For example, charging a 1000pF load to 16V in 25nsec requires an 0.8A current from the device power supply.

To guarantee low supply impedance over a wide frequency range, a parallel capacitor combination is recommended for supply bypassing. Low-inductance ceramic MLC capacitors with short lead lengths (< 0.5-in.) should be used. A 1.0 μF film capacitor in parallel with one or two 0.1 μF ceramic MLC capacitors normally provides adequate bypassing.

GROUNDING

The TC1426 and TC1428 contain inverting drivers. Individual ground returns for the input and output circuits or a ground plane should be used. This will reduce negative feedback that causes degradation in switching speed characteristics.

INPUT STAGE

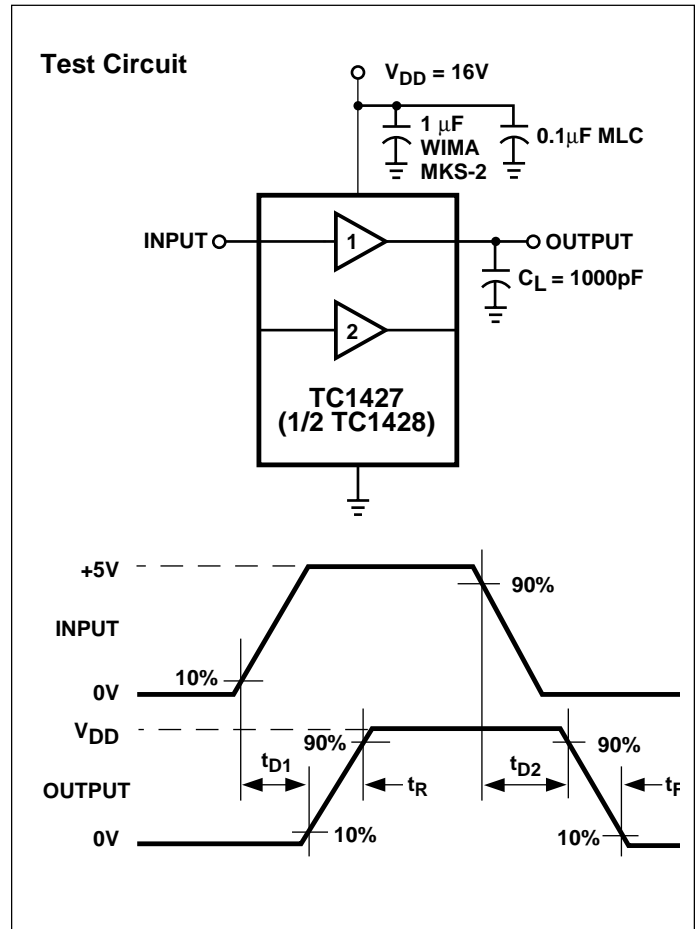
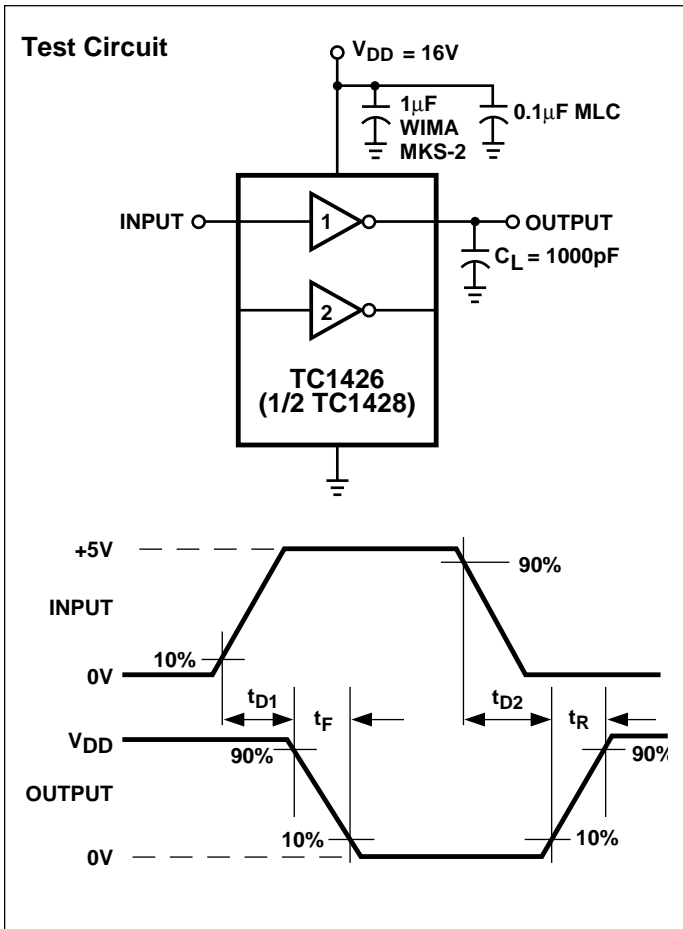
The input voltage level changes the no-load or quiescent supply current. The N-channel MOSFET input stage transistor drives a 2.5 mA current source load. With a logic "1" input, the maximum quiescent supply current is 9mA. Logic "0" input level signals reduce quiescent current to 500 μA maximum. **Unused driver inputs must be connected to V_{DD} or GND.** Minimum power dissipation occurs for logic "0" inputs for the TC1426/27/28.

The drivers are designed with 100mV of hysteresis. This provides clean transitions and minimizes output stage current spiking when changing states. Input voltage thresholds are approximately 1.5V, making logic "1" input any voltage greater than 1.5V up to V_{DD} . Input current is less than 1 μA over this range.

The TC1426/27/28 may be directly driven by the TL494, SG1526/27, TC38C42, TC170 and similar switch-mode power supply integrated circuits.

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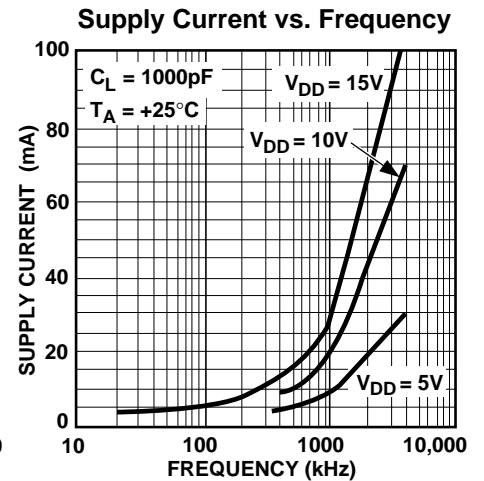
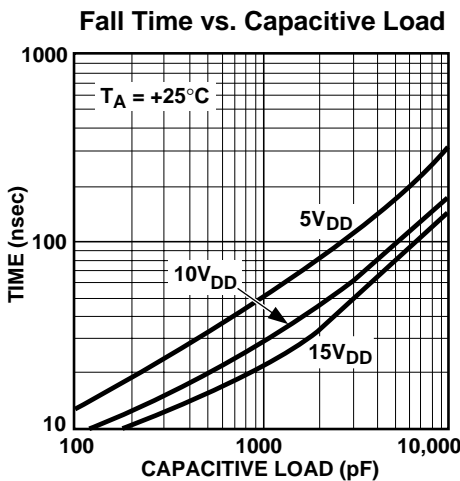
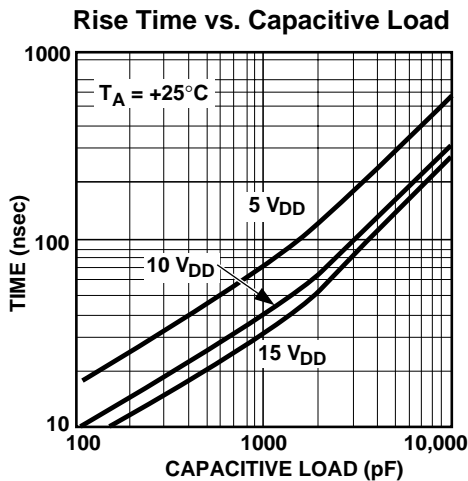
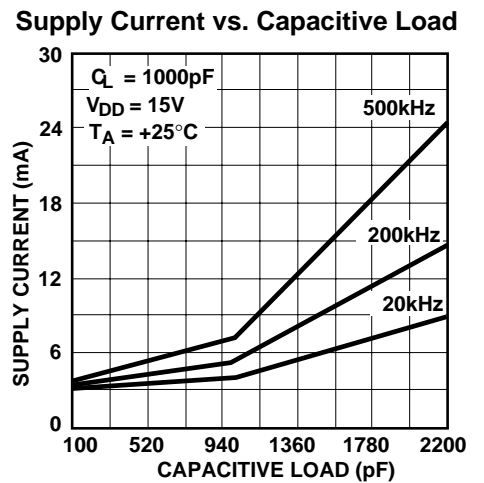
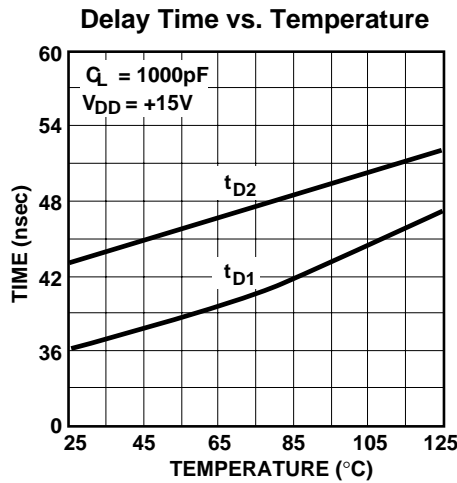
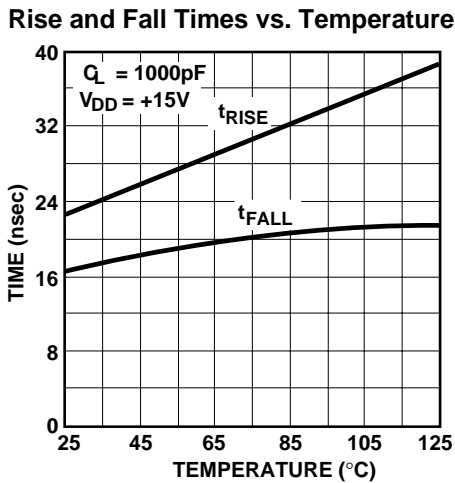
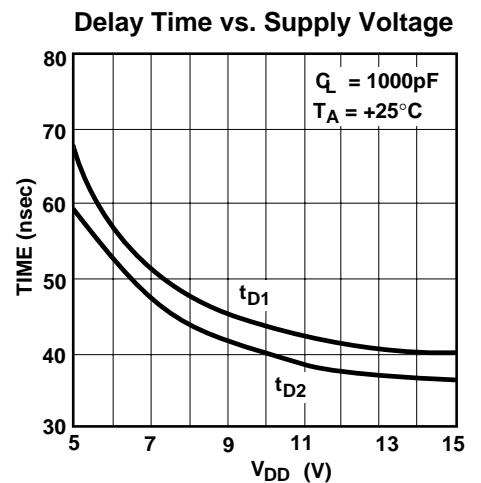
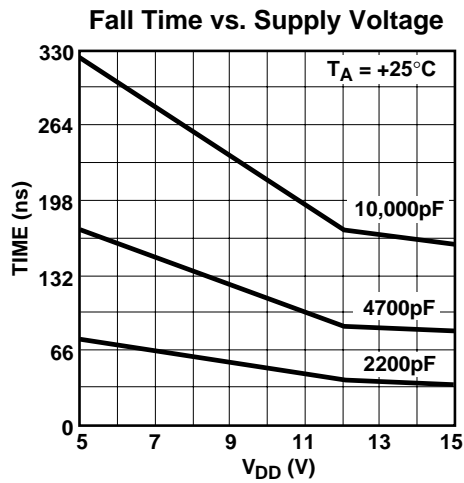
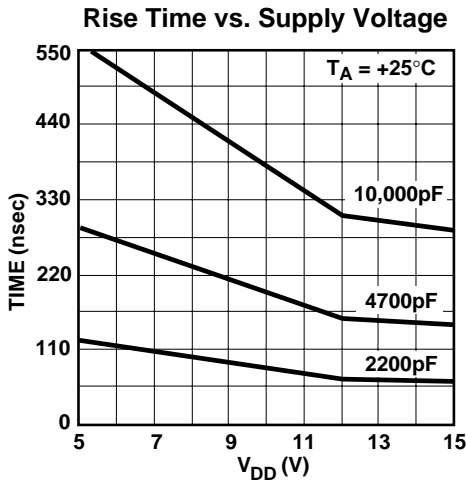
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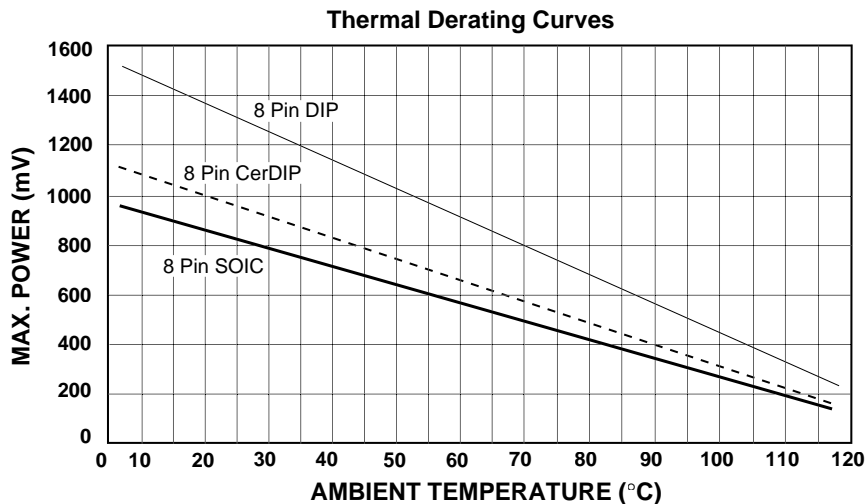
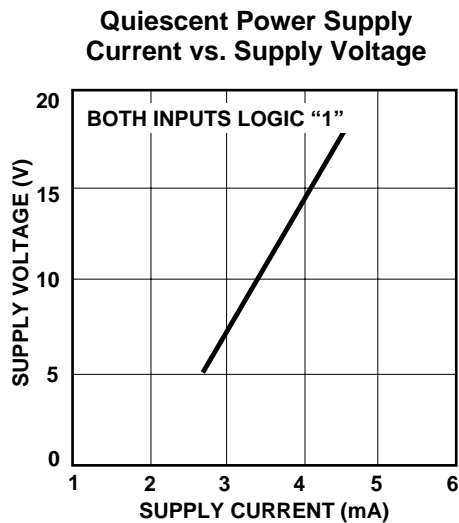
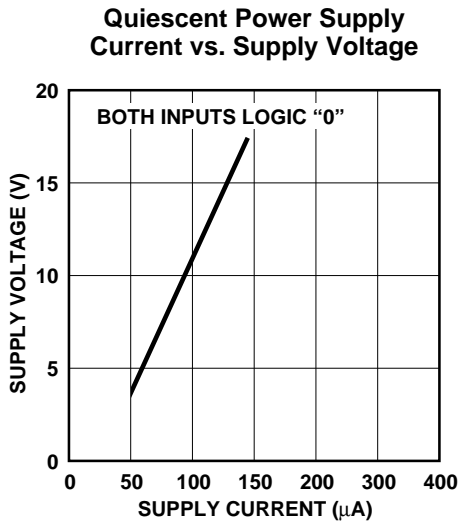
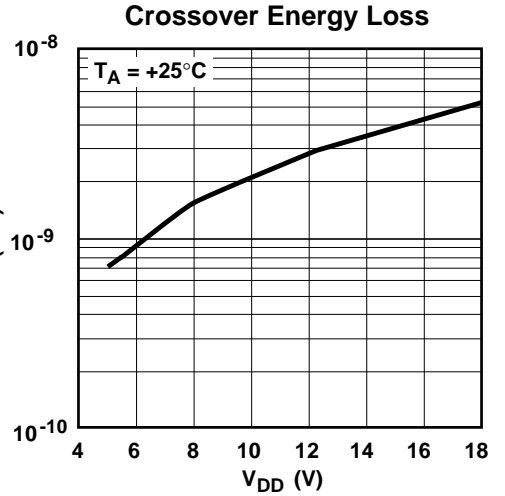
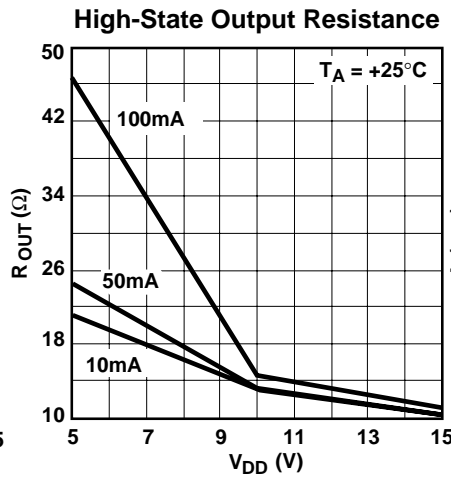
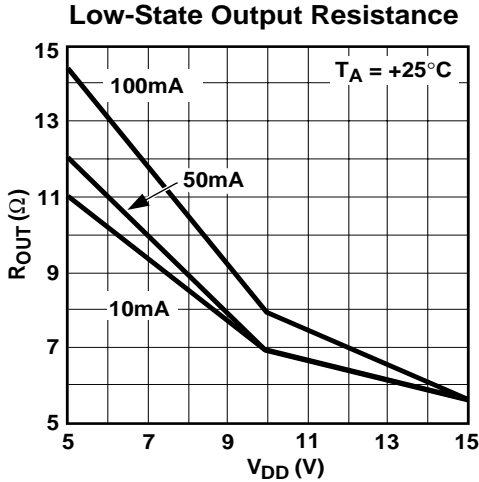
TYPICAL CHARACTERISTICS



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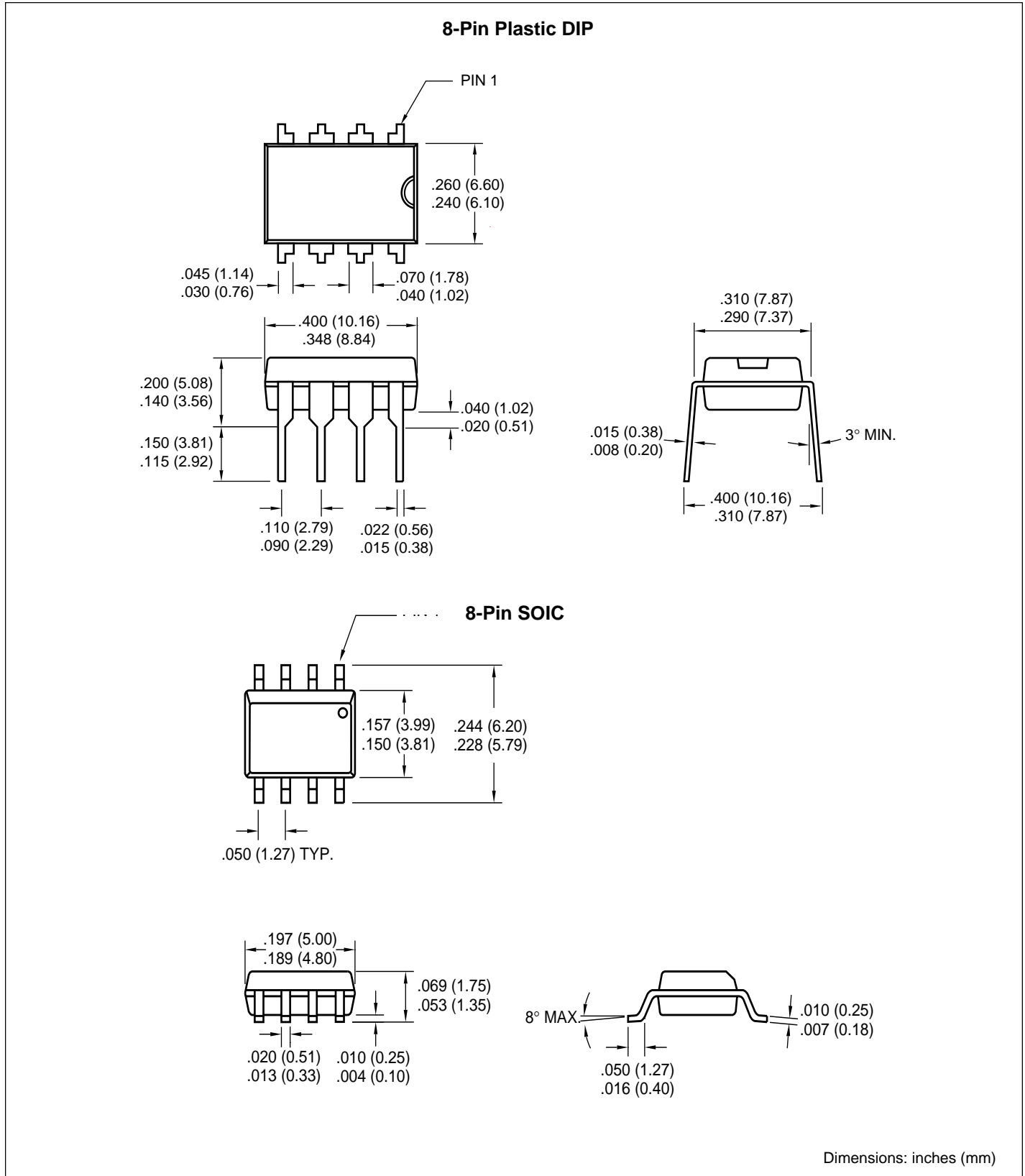
TYPICAL CHARACTERISTIC (Cont.)



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TC1427
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